



# Product End-of-Life Disassembly Instructions

**Product Category:** Networking Equipment

**Marketing Name / Model**

**[List multiple models if applicable.]**

H3C S10500 4-Port 40GBASE Ethernet Optical Interface Module(QSFP+,MPO)(SF) (LSUM1QGS4SF0)

HP 10500 4-port 40GbE QSFP+ SF Module (JC757A)

HP 10500 4-port 40GbE QSFP+ SF TAA-compliant Module (JG346A)

H3C S7500E 4 Port 40GBASE Ethernet Optical Interface Module(QSFP+,MPO)(SC) (LSQM1QGS4SC0)

HP 7500 4-port 40GbE QSFP+ SC Module (JC792A)

H3C S10500 8-Port 40GBASE Ethernet Optical Interface Module(QSFP+,MPO)(SF) (LSUM1QGS8SF0)

HP 10500 8-port 40GbE QSFP+ SF Module (JG392A)

HP 10500 8-port 40GbE QSFP+ SF TAA-compliant Module (JG393A)

H3C S7600-X 8-Port 40GBASE Ethernet Optical Interface Module(QSFP+,MPO)(SC) (LSQM1QGS8SC3)

H3C S7600-X 4-Port 40GBASE Ethernet Optical Interface Module(QSFP+,MPO)(SC) (LSQM1QGS4SC3)

H3C S7600-X 8-Port Enhanced 10GBASE Ethernet Optical Interface Module(SFP+,LC)(EB) (LSQM1TGS8EB3)

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description                                                                         | Notes                                                                                 | Quantity of items included in product |
|------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)                         | With a surface greater than 10 sq cm                                                  | 1                                     |
| Batteries                                                                                | All types including standard alkaline and lithium coin or button style batteries      | 0                                     |
| Mercury-containing components                                                            | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0                                     |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm                      | Includes background illuminated displays with gas discharge lamps                     | 0                                     |
| Cathode Ray Tubes (CRT)                                                                  |                                                                                       | 0                                     |
| Capacitors / condensers (Containing PCB/PCT)                                             |                                                                                       | 0                                     |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height |                                                                                       | 0                                     |
| External electrical cables and cords                                                     |                                                                                       | 0                                     |
| Gas Discharge Lamps                                                                      |                                                                                       | 0                                     |
| Plastics containing Brominated Flame Retardants                                          |                                                                                       | 0                                     |

|                                                                                                      |                                                                                  |   |
|------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------|---|
| weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)             |                                                                                  |   |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Components and waste containing asbestos                                                             |                                                                                  | 0 |
| Components, parts and materials containing refractory ceramic fibers                                 |                                                                                  | 0 |
| Components, parts and materials containing radioactive substances                                    |                                                                                  | 0 |

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|------------------|---------------------------|
| Screw driver     | 2 #                       |
|                  |                           |

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on sheet metal 1 and 2, and then remove sheet metal 1 and 2
2. Unscrew the screws on heat sink 3, and then remove heat sink 3
3. Unscrew the screws on pcb 5, and then remove pcb 5
4. Unscrew the screws on guiding set 4, and then remove guiding set 4
5. Remove shielding finger 6 from panel 7
6. Remove film 8 from panel 7

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

